Technical Document

LED Specification

EC/Opto Group

GW5BTC65K00 LED for Lighting Applications

Product Specification April 2010

"Mini- Zenigata" Module: High-output (3.6 W), 4000 K LED Module (230 lm) High Color Rendering (85 CRI) suited for lighting applications



SHARP

Spec No.	DG-09Z028A
Issue	16-Apr-10

SPECIFICATIONS

Product Type

Light Emitting Diode Module

Model No.

GW5BTC65K00

*These specifications contain<u>14</u> pages including the cover and appendix. If you have any objections, please contact us before issuing purchasing order.

CUSTOMERS ACCEPTANCE

DATE: _____

BY: _____

PRESENTED

BY: M.Katoh Dept. General Manager

REVIEWED BY:

PREPARED BY:

Development Department II System Device Division III Electronic Components And Devices Group SHARP CORPORATION

Model No. **GW5BTC65K00**



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• When using the products covered herein, please observe the conditions written herein and the precautions outlined in the following paragraphs. In no event shall the company be liable for any damages resulting form failure to strictly adhere to these conditions and precautions.

(1) Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.

(2) The products covered herein are designed and manufactured for the following application areas. When using the products covered herein for the equipment listed in paragraph (3), even for the following application areas, be sure to observe the precautions given in Paragraph (3). Never use the products for the equipment listed in Paragraph (4).

- \cdot Office electronics
- ·Instrumentation and measuring equipment
- Machine tools
- Audiovisual equipment
- · Home appliances
- ·Communication equipment other than for trunk lines
- (3) These contemplating using the products covered herein for the following

equipment which demands high reliability, should first contact a sales representative of the company and then accept responsibility for incorporating into the design fail-safe operation, redundancy, and other appropriate measures for ensuring reliability and safety of the equipment and the overall system.

·Control and safety devices for airplanes, trains, automobiles, and other

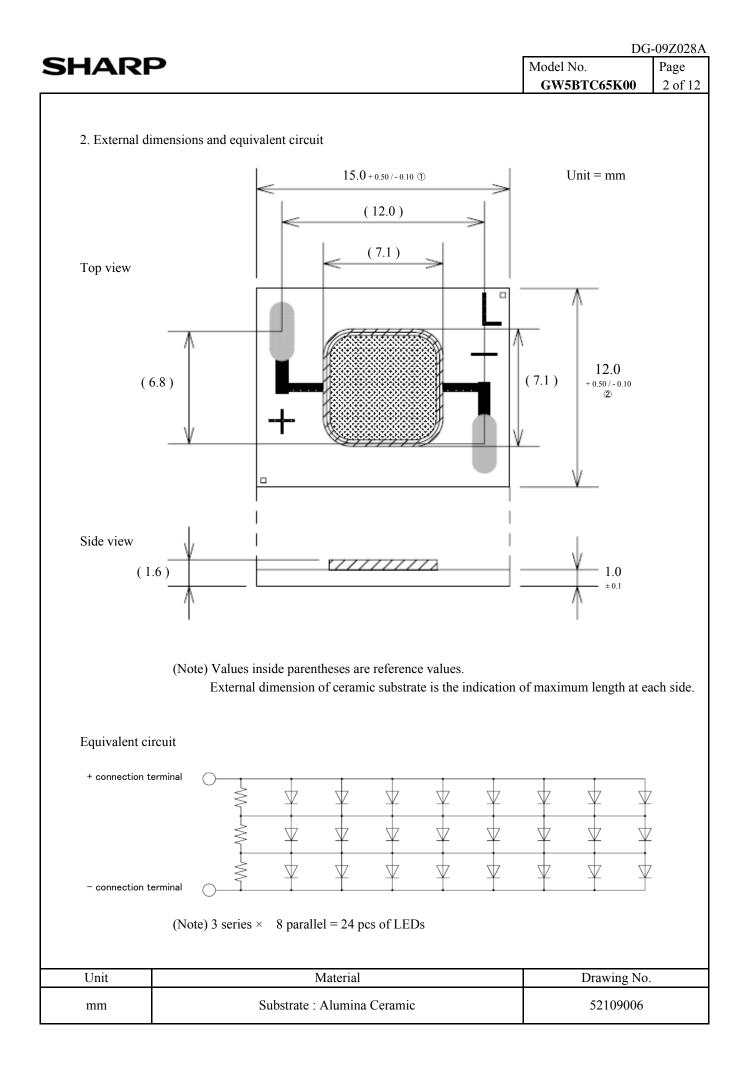
- transportation equipment
- · Mainframe computers
- ·traffic control systems
- ·Gas leak detectors and automatic cutoff devices
- ·Rescue and security equipment
- ·Other safety devices and safety equipment, etc.

(4) Do not use the products covered herein for the following equipment which

- demands extremely high performance in terms of functionality, reliability, or accuracy.
 - ·Aerospace equipment
 - ·Communications equipment for trunk lines
 - · Control equipment for the nuclear power industry
 - ·Medical equipment related to life support, etc.
- (5) please direct all queries and comments regarding the interpretation of the above four Paragraphs to a sales representative of the company.

 Please direct all queries regarding the products covered herein to a sales representative of the company.

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GW5BTC65K00 specifications		
 Application These specifications apply to the light emitting diode module Model No. GW [High color rendering Daylight (from InGaN Blue LED chip + Phosphor) L Main application : Lighting 		
2. External dimensions and equivalent circuit Refer	to Page 2.	
3. Ratings and characteristics Refer	to Page 3 - 5	
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3. Ratings and characteristics

3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power Dissipation *1,4	Р	4.6	W
Forward Current *1,4	I _F	400	mA
Reverse Voltage *2,4	V _R	-15	V
Operating Temperature *3	T _{opr}	- 30 ~ + 90	°C
Storage Temperature	T _{stg}	- 40 ~ + 100	°C

*1 Power dissipation and forward current are the value when the module temperature is set lower than the rating by using an adequate heat sink.

*2 Voltage resistible at initial connection error

(Not dealing with the possibility of always-on reverse voltage.)

*3 Case temperature Tc (Refer to measuring point for case temperature in the next page.) Refer to "Derating curve" in the next page as for operating current.

*4 $T_c = 25 \ ^{\circ}C$

3-2. Electro-optical characteristics

 $(T_c = 25 \ ^{\circ}C)$

Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Forward Voltage *5	$V_{\rm F}$	$I_{\rm F} = 360 {\rm mA}$	9.0	(10.2)	11.5	V
Luminous Flux *6	Φ	$I_{\rm F} = 360 {\rm mA}$	180	(230)	-	lm
Chromaticity Coordinates *7	Х	$I_{\rm F} = 360 {\rm mA}$	-	(0.313)	-	-
Chromatienty Coordinates • 7	У	$I_{\rm F} = 500 {\rm mA}$	-	(0.332)	-	-
Color Temperature	-	$I_{\rm F} = 360 {\rm mA}$	(6020)	(6500)	(7040)	K
General Color Rendering Index *8	Ra	$I_{\rm F} = 360 {\rm mA}$	81	(85)	-	-

(Note) Values inside parentheses are shown for reference purpose only.

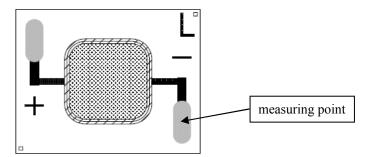
- *5 (After 20 ms drive, Measurement tolerance: ± 3 %)
- *6 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 20 %)
- *7 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 0.01)
- *8 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 4)

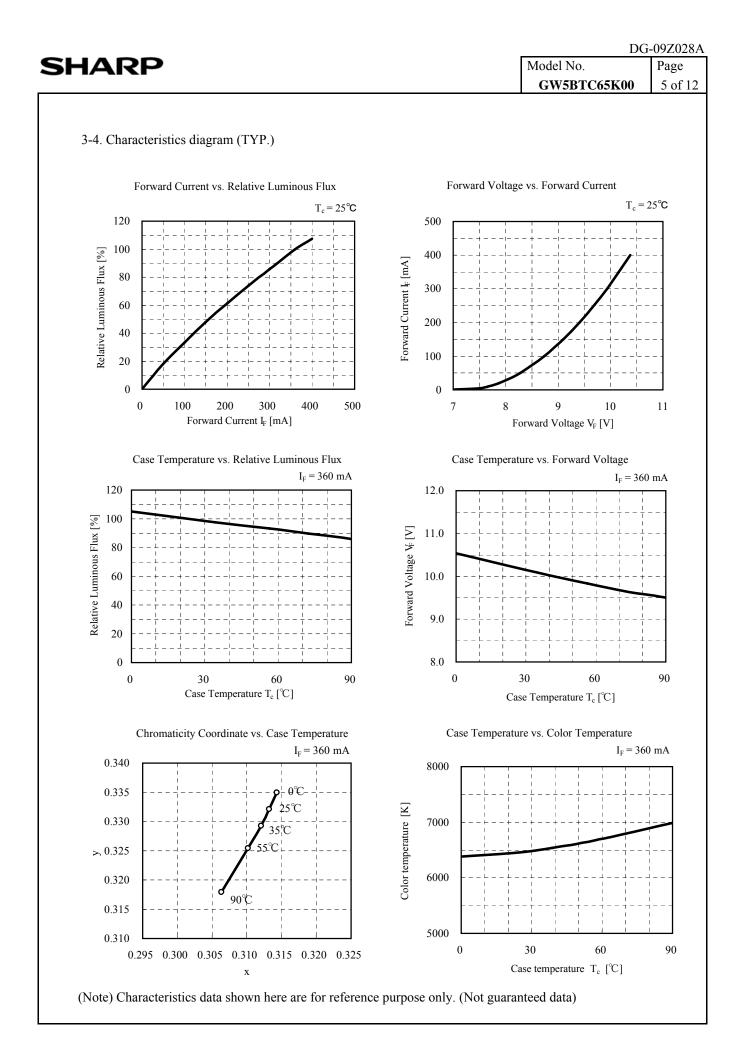
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3-3. Derating	curve		
	Forward Current Derating Curve		
₹ ⁵⁰⁰			
Forward Current I _F [mA] 000 000 000 000 000 000 000 000 000 00			
1 1 300			
		- + - + - + - + - + - + - + - + - + - +	
ට 200 පු		- +	
≥ 100			

(Note) To keep the case temperature lower than the rating, enough heat-radiation performance needs to be secured by using an adequate heat sink.

Case Temperature T_c [°C]

(Measuring point for case temperature)





4. Reliability

The reliability of products shall be satisfied with items listed below.

4-1.7	Fest items and test condit	ions	Co	nfidence le	vel: 90 %
No.	Test item	Test conditions	Samples	Defective	LTPD
			n	С	(%)
1	Temperature Cycle	- 40 °C(30 min) \sim + 100 °C(30 min), 100 cycles			
			11	0	20
2	Temperature Humidity	$T_{stg} = +60 \text{ °C}, RH = 90 \text{ \%}, Time = 1000 \text{ h}$			
	Storage		11	0	20
3	High Temperature	$T_{stg} = +100$ °C, Time = 1000 h			
	Storage		11	0	20
4	Low Temperature	$T_{stg} = -40$ °C, Time = 1000 h			
	Storage		11	0	20
5	Steady State Operating	$T_c = 60 \text{ °C}, I_F = 400 \text{ mA}, \text{ Time} = 1000 \text{ h}$			
	Life		11	0	20
6	Shock	Acceleration: 15000 m/s^2 , Pulse width: 0.5 ms			
		Direction: 3 directions (X, Y and Z)			
		3 trials in each direction	5	0	50
7	Vibration	Frequency: 100 to 2000 Hz for 4 minutes per trial			
		Acceleration: 200 m/s ²			
		Direction: 3 directions (X, Y and Z)			
		4 trials in each direction	5	0	50

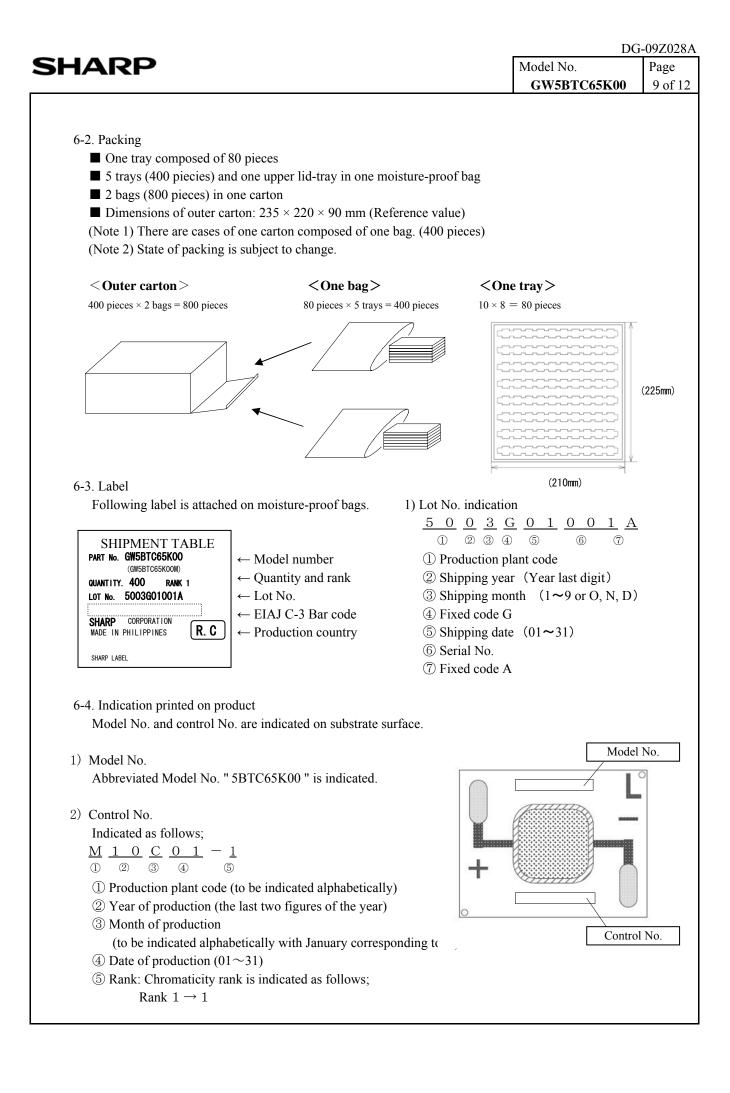
4-2. Failure criteria

No.	Parameter	Symbol	Failure criteria
1	Forward Voltage	$V_{\rm F}$	$V_F > U.S.L \times 1.1$
2	Luminous Flux	Φ	Φ < Initial value × 0.7

(Note) U.S.L. stands for Upper Specification Limit.

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5. Qu	ality level			
	Applied standard SO2859-1			
A	-	ion mpling plan, level S-4. and defect criteria		
No.	Item	Defect criteria	Classification	AQL
1	No radiation	No light emitting	Major defect	0.1%
1	No radiation Electro-optical characteristics	No light emitting Not conforming to the specification (Forward voltage, Luminous flux and Chromaticity)	-	0.1%
	Electro-optical	Not conforming to the specification	-	0.1%
2	Electro-optical characteristics External	Not conforming to the specification (Forward voltage, Luminous flux and Chromaticity) Not conforming to the specified dimensions	Minor defect	0.1%

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6. Supplements							
6-1. Chromaticity ra	ank table				(Te	olerance: $x,y \pm 0$.	01)
	$(I_F = 3)$	60 mA, T _c	= 25 °C)				
Range	Chromaticity						
	Point 1 Point 2	Point 3	Point 4				
x	0.3028 0.3058	0.3217	0.3205				
у	0.3304 0.3161	0.3316	0.3481				
	C1	1.					
Rank	Chromaticity Point 1 Point 2	Point 3	tes Point 4				
	0.3028 0.3058	0.3138	0.3117				
$1 \qquad \frac{x}{y}$	0.3304 0.3161	0.3238	0.3393				
v	0.3117 0.3138	0.3217	0.3205				
$2 \qquad x \qquad y \qquad y$	0.3393 0.3238	0.3316	0.3481				
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i,				1			
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> 0.330							
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	\mathbf{V}_{i} \mathbf{V}_{i} \mathbf{V}_{i} \mathbf{V}_{i}						
0.320		K 1 ↓ 1 ↓ ↓	۱.	I I			
0.520			i i	1 1 1			
		N I	1	6000K			
	·	\ \ \	400K	· · · · · · · · · · · · · · · · · ·			
	`\ 6800K			· · ·			
0.310	· · · ·	\					
0.300	0.310		0.32	20	0.330		



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7. Precautions	
① Storage conditions	
Please follow the conditions below.	
• Before opened: Temperature 5 \sim 30 °C, Relative humidity less that	n 60 %.
(Before opened LED should be used within a year)	
• After opened: Temperature 5 \sim 30 °C, Relative humidity less than	60 %.
(Please apply soldering within 1 week)	
•After opened LED should be kept in an aluminum moisture proof ba	g with a moisture
absorbent material (silica gel).	-
 Avoid exposing to air with corrosive gas. 	
If exposed, electrode surface would be damaged, which may affect s	oldering.
② Usage conditions	
This product is not designed for the use under any of the following c	onditions.
Please confirm performance and reliability well enough if you use ur	der any of the following conditions
• In a place with a lot of moisture, dew condensation, briny air, and o (Cl, H ₂ S, NH ₃ , SO ₂ , NO _X , etc.)	orrosive gas.
• Under the direct sunlight, outdoor exposure, and in a dusty place.	
• In water, oil, medical fluid, and organic solvent.	
③ Heat radiation	
If forward current (I_F) is applied to single-state module at any curren	t, there is a risk of damaging LED
or emitting smoke.	
Equip with specified heat radiator, and avoid heat stuffed inside the n	nodule.
④ Installation	
Material of board is alumina ceramic. If installed inappropriately, trou	ble of no radiation may occur due t
board crack or overheat. Please take particular notice for installation.	
Refer to the following cautions on installation.	
• Apply thermolysis adhesive, adhesive sheet or peculiar connector	
In case of applying adhesive or adhesive sheet only, check the effe	
If LED comes off from heat radiator, unusual temperature rise ent device deterioration, coming off of solder at leads, and emitting sr	
 When LED device is mechanically fixed or locked, Please take int 	
attachment due to fail from stress.	o consideration regarding the metho
 Avoid convexly uneven boards. 	
Convex board is subject to substrate cracking or debasement of he	at release
 It is recommended to apply adhesive or adhesive sheet with high t 	
for radiation of heat effectively.	
 Please take care about the influence of color change of adhesive o 	adhesive sheet in initial and long to
period, which may affect light output or color due to change of rel	

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 Do not touch resin part including white resin part on the surface of Li No light emission may occur due to damage of resin or cutting wire of When using tweezers, please handle by ceramic substrate part and av For mounting, please handle by side part of ceramic or the specified a 	of LEDs by outer force. oid touching resin part.	
5 Connecting method		
In case of solder connecting method, follow the conditions mentioned b • Use Soldering iron with thermo controller (tip temperature 380 °C), w		
 Secure the solderwettability on whole solder pad and leads. During the soldering process, put the ceramic board on materials whose not to radiate heat of soldering. 	se conductivity is poor enoug	h
• Warm up (with using a heated plate) the substrate is recommended bet (preheat condition: 100 °C \sim 150 °C, within 60 sec)	fore soldering.	
• Avoid touching a part of resin with soldering iron.		
• This product is not designed for reflow and flow soldering.		
• Avoid such lead arrangement as applying stress to solder-applied area		
• Please do not detach solder and make re-solder.		
Please solder evenly on each electrodes.		
Please prevent flux from touching to resin.		
6 Static electricity		
This product is subject to static electricity, so take measures to cope with	h it.	
Install circuit protection device to drive circuit, if necessary.		
⑦ Drive method		
• Any reverse voltage cannot be applied to LEDs when they are in operation	ation or not.	
Design a circuit so that any flow of reverse or forward voltage can not b when they are out of operation.		
• Module is composed of LEDs connected in both series and parallel. Constant voltage power supply runs off more than specified current am	ount due to lowered V_F	
caused by temperature rise. Constant current power supply is recommended to drive.		
® Cleaning		
Avoid cleaning, since silicone resin is eroded by cleaning.		
O Color-tone variation O		
Chromaticity of this product is monitored by integrating sphere right aft	er the operation.	
Chromaticity varies depending on measuring method, light spread condi	-	
Please verify your actual conditions before use.	, <u>i</u>	

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10 Safety		
•Looking directly at LEDs for a long time may result in hurt your eyes.		
•In case that excess current (over ratings) are supplied to the device, hazardo	ous phenomena including	
abnormal heat generation, emitting smoke, or catching fire can be caused.	F	
Take appropriate measures to excess current and voltage.		
•In case of solder connecting method, there is a possibility of fatigue failure	by heat.	
Please fix the leads in such case to protect from short circuit or leakage of	electricity caused by conta	act.
•Please confirm the safety standards or regulations of application devices.		
•Please careful not to injure your hand by edge of ceramic substrate.		

① Other cautions

Guarantee covers the compliance to the quality standards mentioned in the Specifications, however it does not cover the compatibility with application of the end-use, including assembly and usage environment.

In case any quality problems occurred in the application of end-use, details will be separately discussed and determined between the parties hereto.

Opto Specification

Opto/EC Group

SHARP.

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